



1 Description

The RedRock® RR132-1B12-551/552 and RR132-1B13-551/552 are digital magnetic sensors ideal for use in medical, industrial, automotive, and consumer applications. It is based on patented Tunneling Magneto-resistance (TMR) technology with seamless CMOS integration.

The RR132-1B12-551/552 and RR132-1B13-551/552 feature an operate sensitivity of 30 G (3 mT), with an omnipolar magnetic field response. They offer a wide supply voltage range from 1.7 V up to 5.5 V, ideal for applications ranging from small battery-powered electronics to industrial machinery. They have the world's lowest average current drain (50nA) for an active magnetic sensor, operating at 2 Hz and high operating temperature range from -40°C up to +125°C.

2 Features

- ▶ Operate sensitivity of 30 G
- ▶ Lowest Average Current < 50 nA
- ▶ Wide Supply Voltage range of 1.7V – 5.5V
- ▶ Omnipolar Open-Drain Response
- ▶ Operating Frequency of 2 Hz
- ▶ Temperature Rated up to +125°C
- ▶ RoHS & REACH Compliant

3 Applications

- ▶ Proximity Detection
- ▶ Rotary Sensing
- ▶ Fluid Level Detection
- ▶ Door & Lid Closure Detection
- ▶ Utility Meters
- ▶ Portable Medical Devices
- ▶ Motor Controllers
- ▶ Consumer Electronics
- ▶ Wake-Up μ Processor

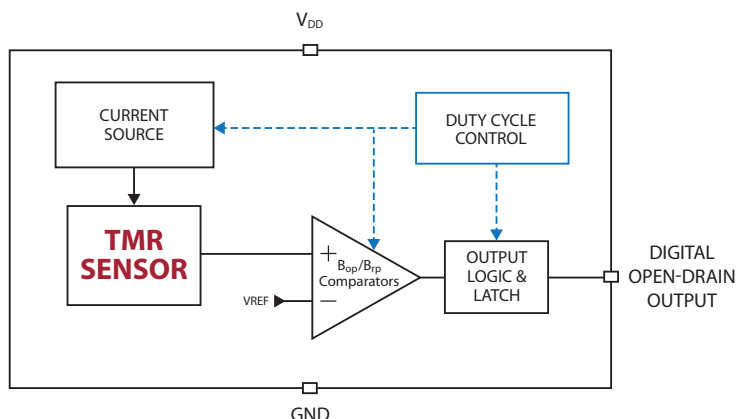
Device Information

Part Series	Package	Body Size (mm)	Temp Rating °C
RR132-1B12-551	SOT-23-3	2.9 x 1.6 x 1.2	-40 to +85
RR132-1B12-552	LGA-4	1.45 x 1.45 x 0.44	-40 to +85
RR132-1B13-551	SOT-23-3	2.9 x 1.6 x 1.2	-40 to +125
RR132-1B13-552	LGA-4	1.45 x 1.45 x 0.44	-40 to +125



Device Packages

Functional Block Diagram
for Digital Open-Drain Output



Device Nomenclature

Ordering Information

RR132-X X X X-YYY			
Series		Package	
Magnetic Polarity Response		Output Response	
1 = Omnipolar	3 = Bipolar/Latch	1: SOT-23-3	
2 = Unipolar		2: LGA-4	
		5: SOT-23-5	
Magnetic Sensitivity (G)		Supply Voltage (V)	
A: Op 9, Rel 5	E: Op 15, Rel 10	5: Open Drain	
B: Op 30, Rel 20	F: Op 70, Rel 50		
C: Op 10, Rel -10		5: 1.7 - 5.5	
Clock Frequency (Hz)		Temp Rating (°C)	
1: 2	5: 250	2: -40 - +85	
2: 10	6: 500	3: -40 - +125	
3: 20	7: 2500		

4 Specifications

4.1 Absolute Environmental Ratings^{1,2}

Parameters	Units	Min	Typ	Max
Operating Temperature (T_{OP}) (RR132-1B12-551/552)	°C	-40		+85
Operating Temperature (T_{OP}) (RR132-1B13-551/552)	°C	-40		+125
Storage Temperature (T_{STG})	°C	-65		+150
Junction Temperature (T_J)	°C			+150
Soldering Temperature (3 cycles, 1 min.) (T_{SOL})	°C			+260
ESD Level Human Body Model per JESD22-A114	V	±4000		
Junction-to-Ambient Thermal Resistance (LGA-4)	°C/W		165	
Junction-to-Ambient Thermal Resistance (SOT-23-3)	°C/W		215	
Maximum Magnetic Field Exposure (B_{MAX})	G			2000

4.2 Absolute Electrical Ratings^{1,2}

Parameters	Units	Min	Typ	Max
Supply Voltage (V_{DD})	V	-0.3		6.0
Open-Drain Output Voltage (Active Low) (V_{OUT-OD})	V	-0.3		6.0
Input and Output Current (I_{IN}/I_{OUT})	mA	-20		20

4.3 Operating Electrical Characteristics for RR132-1B12-551/552 and RR132-1B13-551/552³

Parameters	Units	Min	Typ	Max
Supply Voltage (V_{DD})	V	1.7	3.0	5.5
Power-On Time (t_{ON}) ($V_{DD} > 90\%$)	μs		50	75
Peak Power-On Current	mA			1.4
Output Voltage (High) (V_{OUTH})	V	90% V_{DD}		
Output Voltage (Low) (V_{OUTL})	V			10% V_{DD}
Under Voltage Lockout Threshold Rising V_{DD} ($V_{UVLO-RISE}$)	V		1.60	1.64
Under Voltage Lockout Threshold Falling V_{DD} ($V_{UVLO-FALL}$)	V	1.44	1.53	
Under Voltage Lockout Hysteresis ($V_{UV-HYST}$)	mV		50	
Average Supply Current @ $V_{DD}=1.7$ V, $f_{SW}=2$ Hz (I_{DDAVG}) ⁴	nA		50	900
Average Supply Current @ $V_{DD}=3.0$ V, $f_{SW}=2$ Hz (I_{DDAVG}) ⁴	nA		70	900

Notes:

- Exceeding Absolute Ratings may cause permanent damage to the device.
- Unless otherwise specified, all characteristics are measured at 25°C.
- Unless otherwise specified, $V_{DD} = 1.7$ V to 5.5 V, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$ (1B12), -40°C to $+125^\circ\text{C}$ (1B13). Typical values are $V_{DD} = 3.0$ V and $T_A = +25^\circ\text{C}$.
- Conditions: $t=10$ seconds.



ESD Note: This product uses semiconductors that can be damaged by electrostatic discharge (ESD). When handling, proper ESD precautions should be taken to avoid performance degradation or loss of functionality. Damage due to inappropriate handling is not covered under warranty.

4 Specifications (cont.)

4.4 Operating Characteristics for RR132-1B12-551/552 and RR132-1B13-551/552¹

Parameters	Units	Min	Typ	Max
Switching Frequency (f_{SW})	Hz	1	2	4
Active Mode Time (t_{ACT})	μs		2.6	
Idle Mode Time @ $f_{SW}=2$ Hz (t_{IDLE})	ms	250	500	1000
Operate Point (B_{OPN})	G	23	30	38
Operate Point (B_{OPS})	G	-38	-30	-23
Release Point (B_{RPN})	G	14	20	27
Release Point (B_{RPS})	G	-27	-20	-14
Hysteresis (B_{HYST}) ²	G	5	10	

Notes:

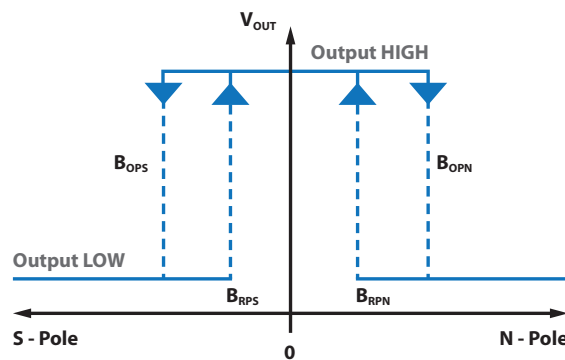
1. Unless otherwise specified, $V_{DD} = 1.7$ V to 5.5 V, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$ (1B12), -40°C to $+125^\circ\text{C}$ (1B13). Typical values are $V_{DD} = 3.0$ V and $T_A = +25^\circ\text{C}$.

2. Conditions: $B_{HYST} = |B_{OP} - B_{RP}|$



ESD Note: This product uses semiconductors that can be damaged by electrostatic discharge (ESD). When handling, proper ESD precautions should be taken to avoid performance degradation or loss of functionality. Damage due to inappropriate handling is not covered under warranty.

5 Output Response vs. Magnetic Flux

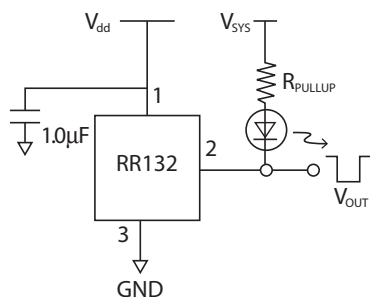


6 Application Information

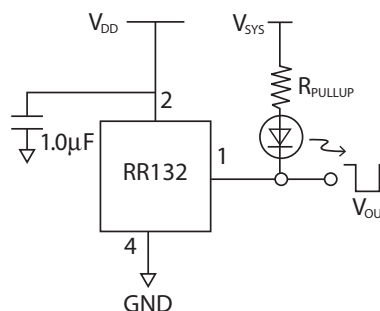
RR132 Application Circuit

The output voltage of the RR132 is active low, meaning that while a sufficiently strong magnetic field is present, the output voltage is low. With the open-drain output, the system voltage can range from ($V_{dd} + 0.3V$) up to absolute max of 6.0Vdc. A decoupling capacitor between the supply voltage and ground is required with placement close to the magnetic sensor. A capacitor with a value of $1.0\mu F$, placed not more than 10 mm from the sensor, is required.

6.1 Application Circuit (SOT-23-3)

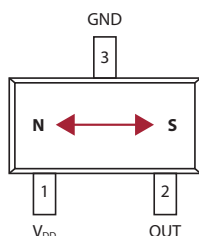


6.2 Application Circuit (LGA-4)

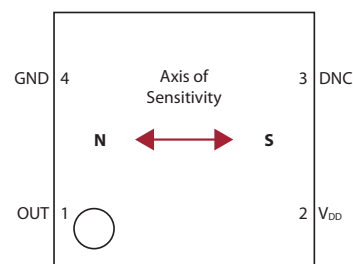


7 Axis of Sensitivity

7.1 SOT-23-3

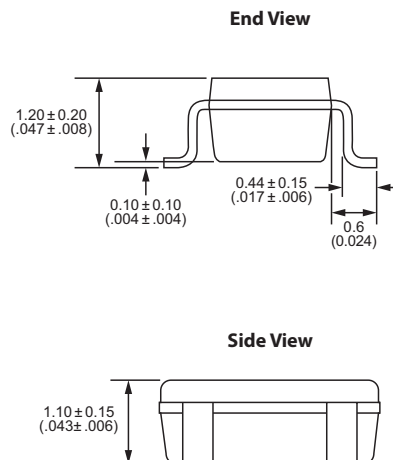
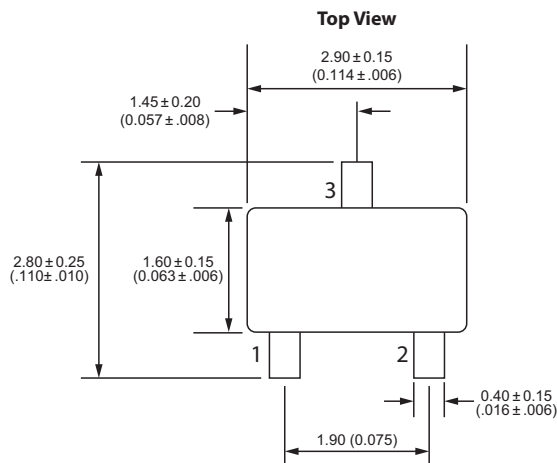


7.2 LGA-4



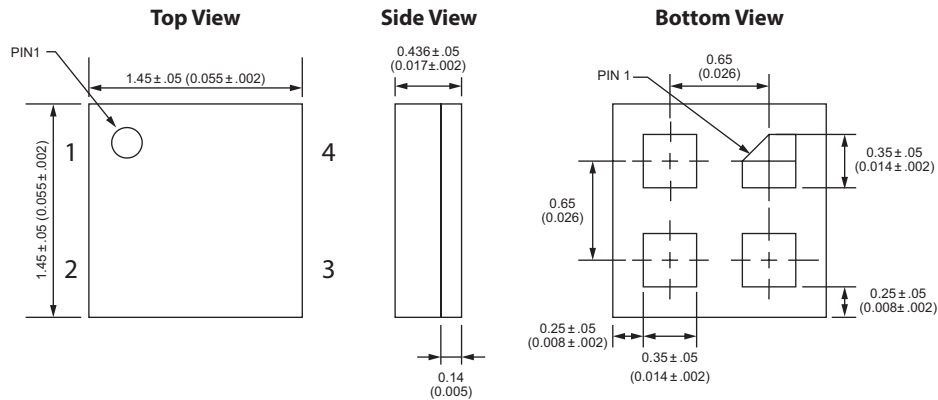
8 Dimensions *Millimeters (Inches)*

8.1 SOT-23-3 Package



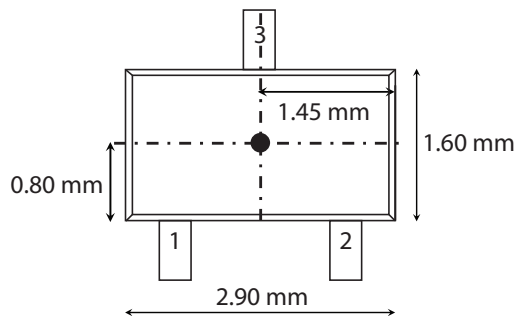
8 Dimensions *Millimeters (Inches)*

8.2 LGA-4 Package

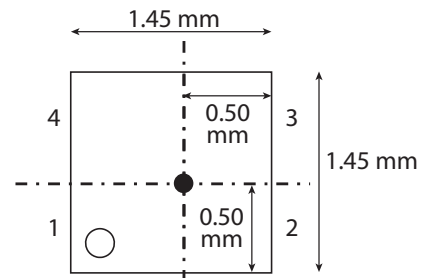


9 TMR Sensor Location

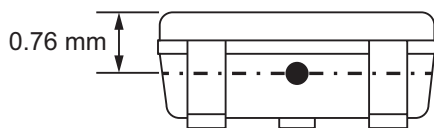
9.1 SOT-23-3 Package



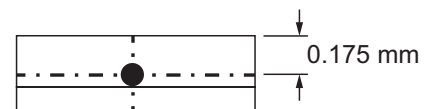
9.2 LGA-4 Package



9.3 SOT Package - Side View



9.4 LGA Package - Side View



10 Output Behavior vs. Magnetic Field Diagrams

Output Behavior vs. Magnetic Field - Omnipolar

Characteristics	Conditions	Output
South Pole	$B < B_{OPS}$ $0 > B > B_{RPS}$	Low (ON) High (OFF)
North Pole	$B > B_{OPN}$ $0 < B < B_{RPN}$	Low (ON) High (OFF)

11 TMR Sensor & Switch Packaging

11.1 SOT-23-3 Tape & Reel Packaging

Standard packaging is Tape & Reel containing 3,000 pieces. MSL Rating is 1.

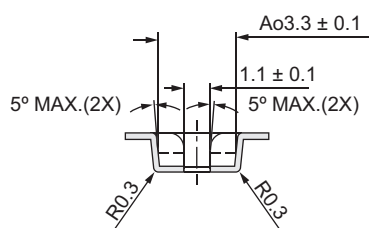
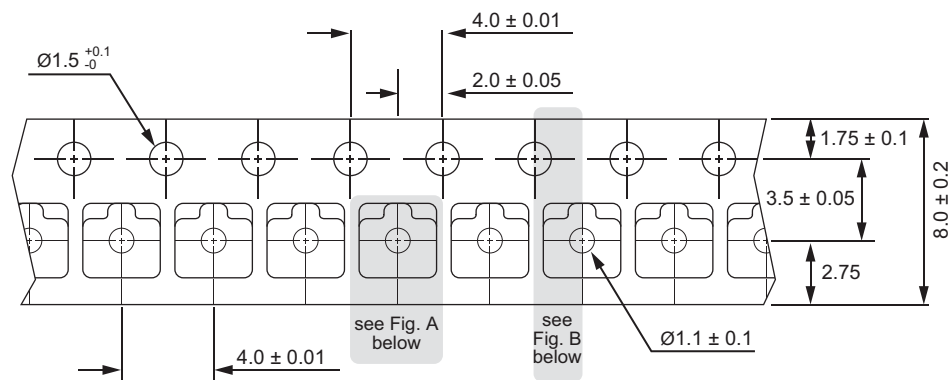


Fig. A

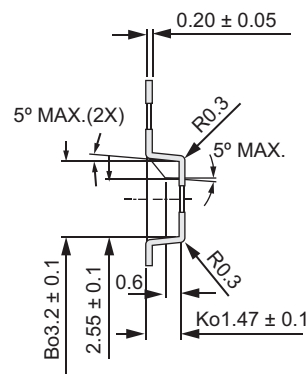
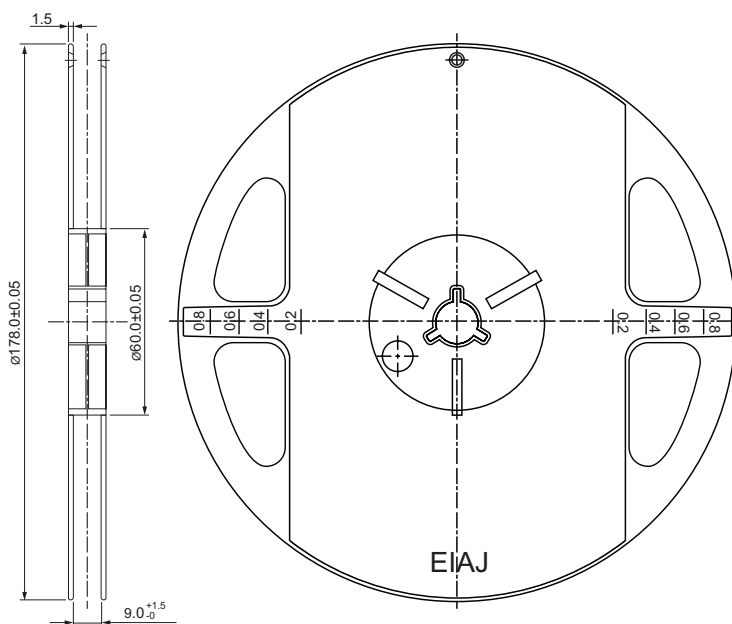
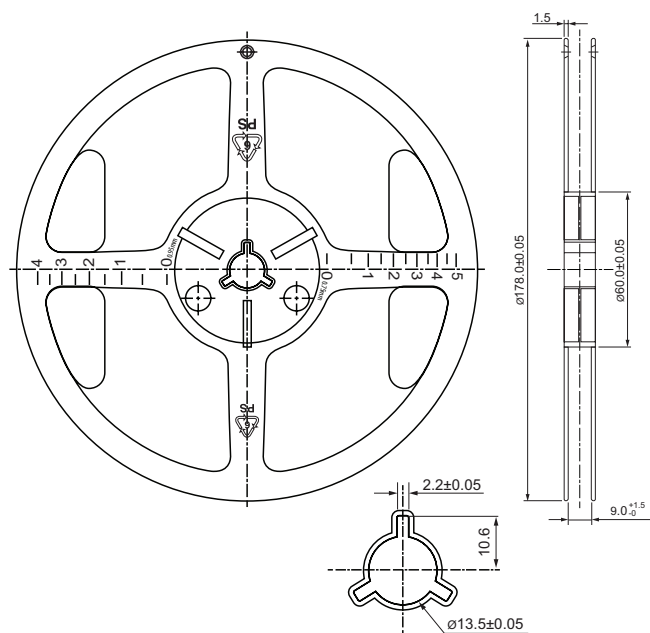


Fig. B



11 TMR Sensor & Switch Packaging

11.2 LGA-4 Tape & Reel Packaging

Standard packaging is Tape & Reel containing 3,000 pieces. MSL Rating is 3.

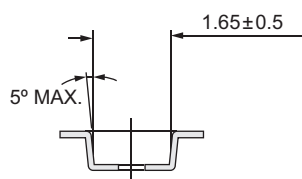
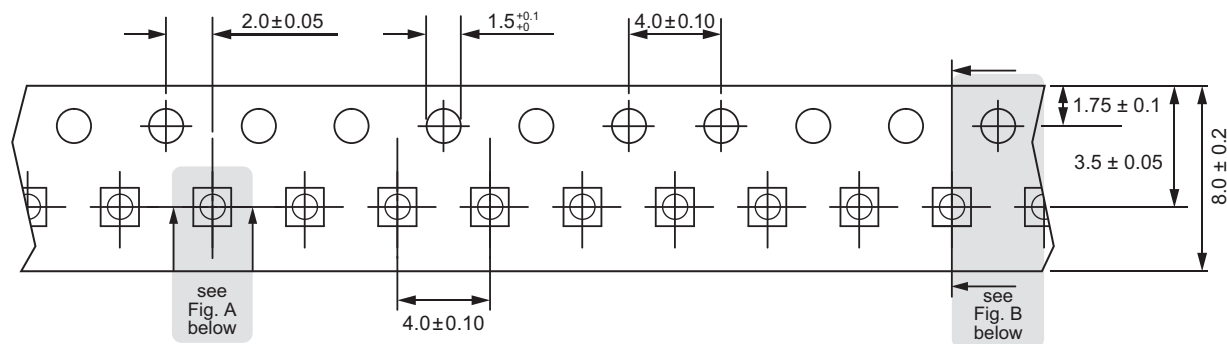


Fig. A

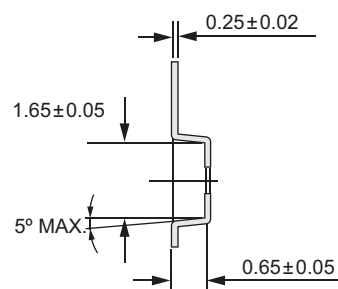
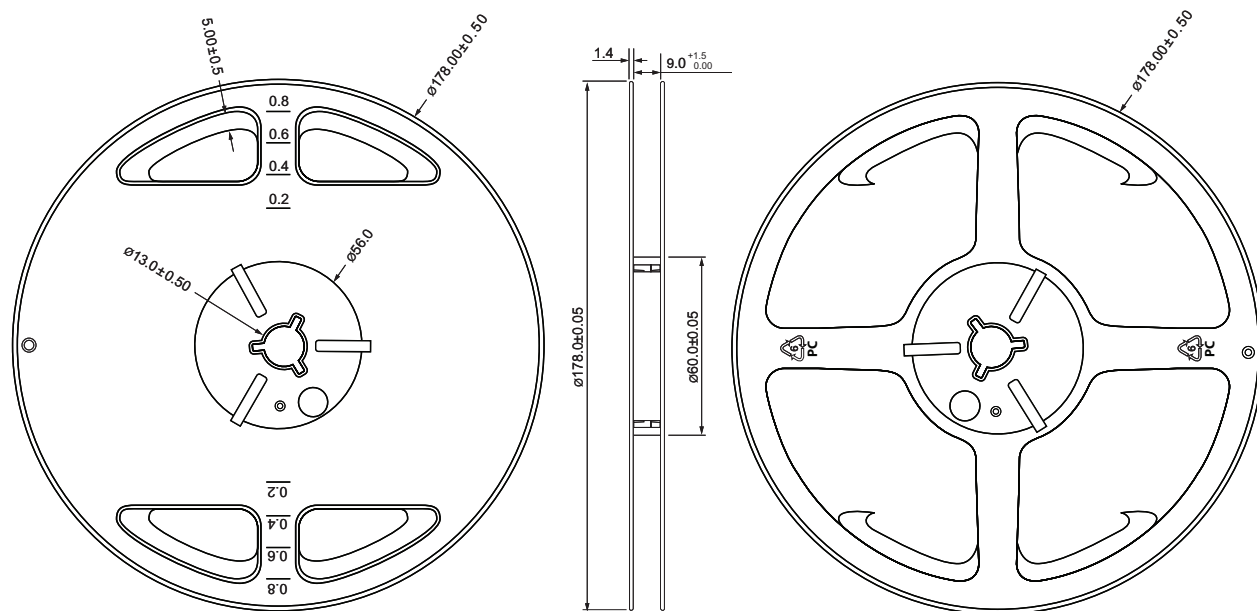


Fig. B



11 TMR Sensor & Switch Packaging

11.3 RedRock TMR Packaging

Box Dimensions – 14x10x6 inches

- Fits 1 to 3 reels = 3000 to 9000 pcs
- Weight for 3000 pcs = 0.90 kilos
- Weight for 9000 pcs = 1.00 kilos

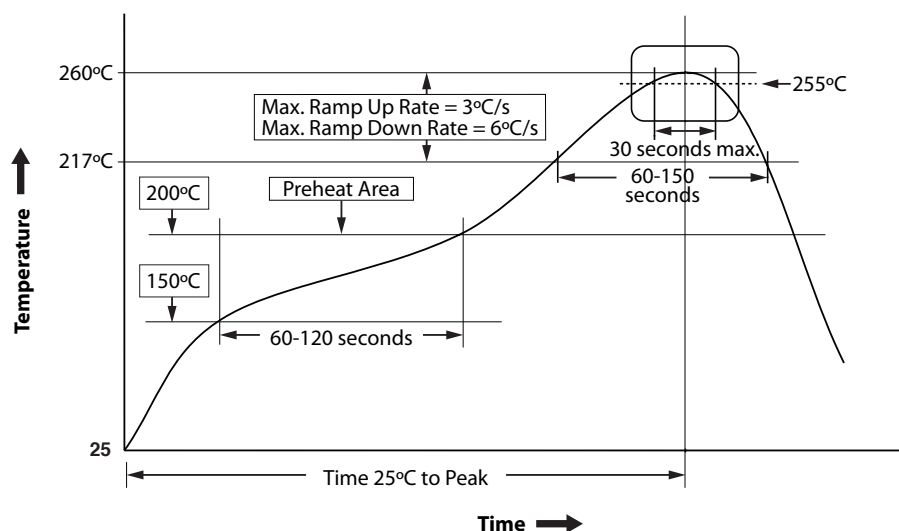
Box Dimensions – 18x14x12 inches

- Fits 4 to 24 reels = 12000 to 72000 pcs
- Weight for 12000 pcs = 1.50 kilos
- Weight for 72000 pcs = 4.90 kilos

12 Suggested Pb-Free Reflow Profile

Notes:

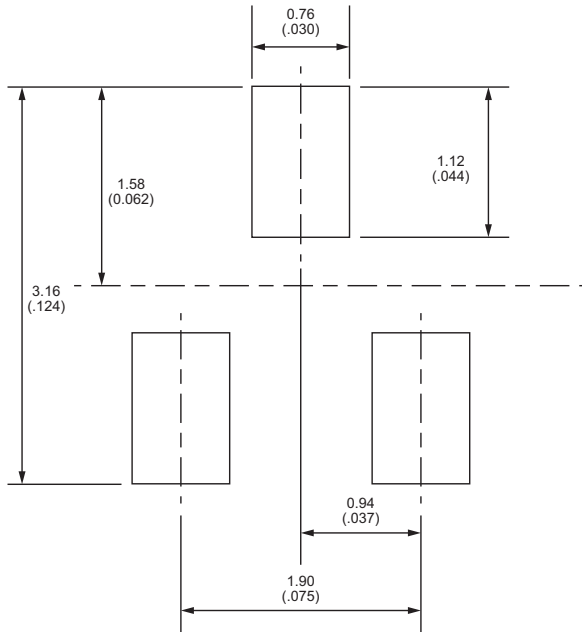
1. Fully compatible with standard no-lead solder profile, 260°C for 30 seconds max (3 cycles max).
2. Profile shown as example. Users are advised to develop their own board-level profile.
3. Suggested Pb-free reflow profile derived from IPC/JEDEC J-STD-020E.
4. Temperature tolerance: +0°C, as measured at any point on the package or leads
5. MSL rating of 1 (SOT-23-3 only) compatible with J-STD-020 or equivalent.
6. MSL rating of 3 (LGA-4 and Leaded LGA-4) compatible with J-STD-020 or equivalent.
7. All temperatures refer to the center of the package, measured on the package body surface that is facing up during assembly reflow (e.g., live-bug). If parts are reflowed in other than the normal live bug assembly reflow orientation (i.e., dead-bug), T_p shall be within $\pm 2^\circ\text{C}$ of the live bug T_p and still meet the T_c requirements, otherwise, the profile shall be adjusted to achieve the latter. To accurately measure actual peak package body temperatures, refer to JEP140 for recommended thermocouple use.
8. Reflow profiles in this document are for classification/preconditioning and are not meant to specify board assembly profiles. Actual board assembly profiles should be developed based on specific process needs and board designs and should not exceed the parameters in this table.



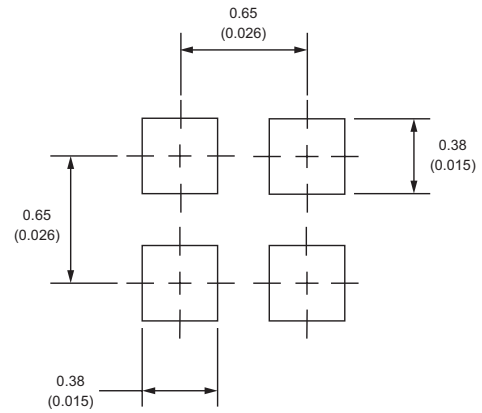
13 Suggested Solder Pad Layout

Dimensions in mm (inches)

13.1 SOT-23-3 Solder Pad Layout



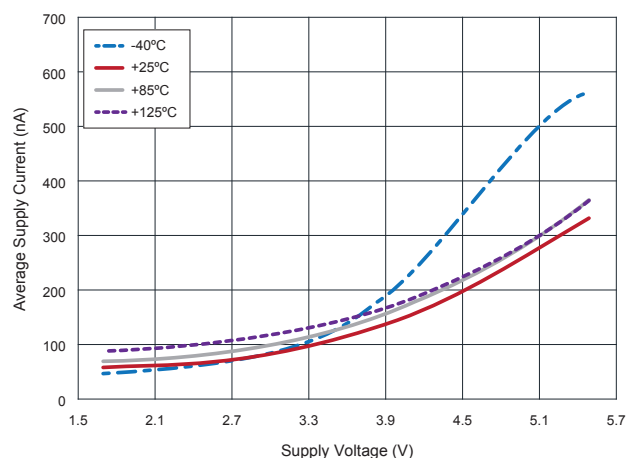
13.2 LGA-4 Solder Pad Layout



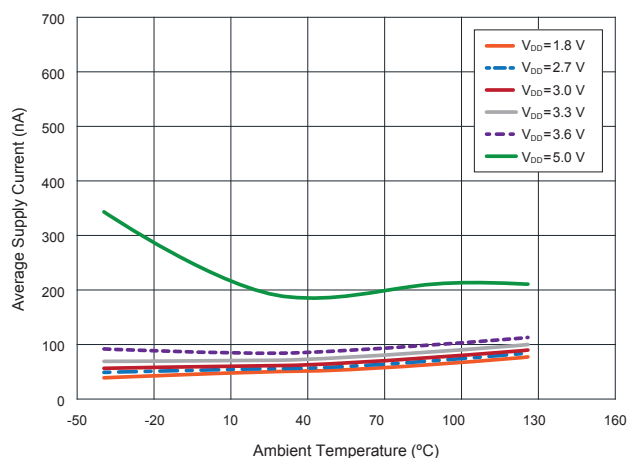
14 Graphs - Typical Electrical Characteristics

$C_{DD} = 1.0 \mu F$ (unless otherwise specified)

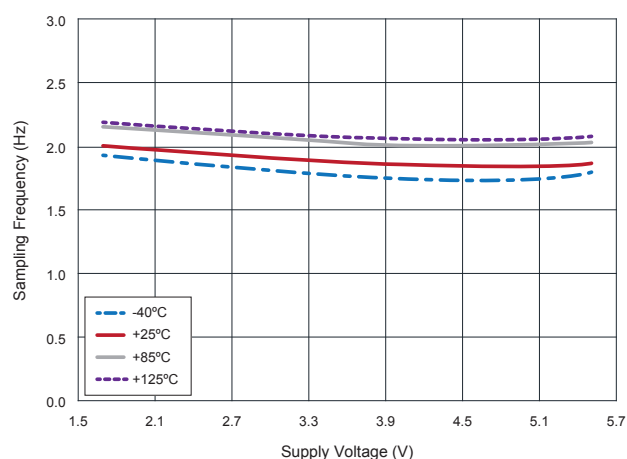
14.1 RR132-1B12-551 / 552
Average Supply Current vs.
Supply Voltage vs. Temperature



14.2 RR132-1B12-551 / 552
Average Supply Current vs.
Temperature vs. Supply Voltage



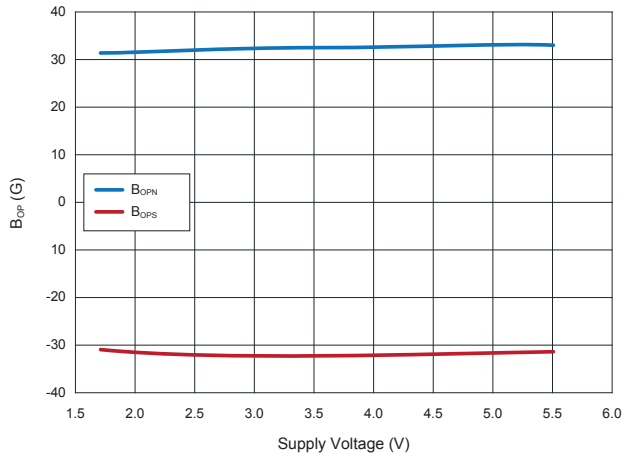
14.3 RR132-1B12-551 / 552
Sampling Frequency vs.
Supply Voltage vs. Temperature



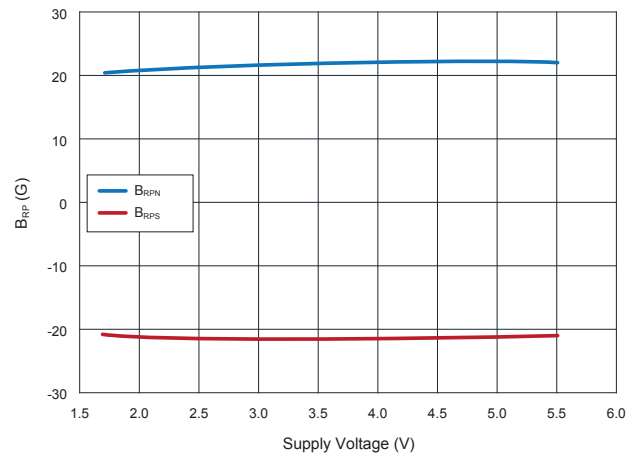
14 Graphs - Typical Magnetic Characteristics

$C_{DD} = 1.0 \mu F$ (unless otherwise specified)

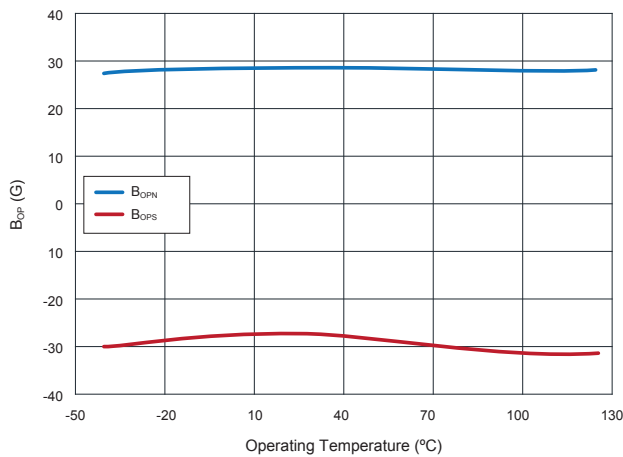
14.4 RR132-1B12-551 / 552
 B_{OPN} (Blue) and B_{OPS} (Red) vs.
Supply Voltage at +25°C



14.5 RR132-1B12-551 / 552
 B_{RPN} (Blue) and B_{RPS} (Red) vs.
Supply Voltage at +25°C



14.6 RR132-1B12-551 / 552
 B_{OPN} (Blue) and B_{OPS} (Red) vs.
Operating Temperature at $V_{DD}=3.0 V$



14.7 RR132-1B12-551 / 552
 B_{RPN} (Blue) and B_{RPS} (Red) vs.
Operating Temperature at $V_{DD}=3.0 V$

